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(54) SEMICONDUCTOR INTEGRATED CIRCUIT AND
 FORMING METHOD THEREOF

(57) Abstract:

PURPOSE: To enable a laminated-type multi-chip module composed of laminated chips to be easily designed as a system.

CONSTITUTION: Semiconductor integrated circuit chips 1, 2, and 3, possessed of pads 32 which have the same attributes and are provided at the same position and vertical wirings 31 formed on the pads 32 and serving as chip connecting electrodes are piled up connecting the pads 32 of the same attributes together through the intermediary of the chip connecting electrodes 31.

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